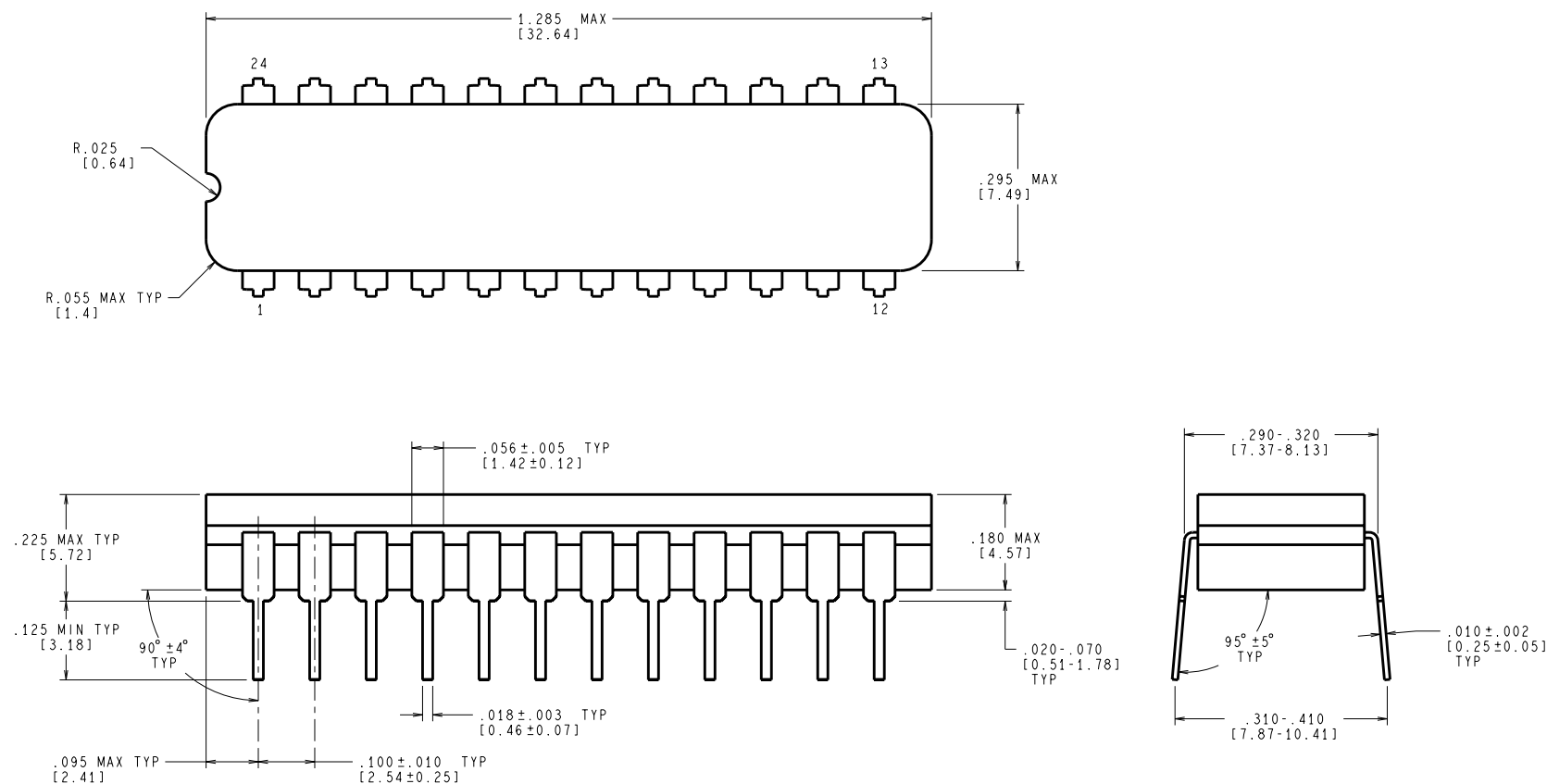


REVISIONS				
LTR	DESCRIPTION	E.C.N.	DATE	BY/APP'D
H	REVISE AND REDRAW PER CURRENT STANDARD; UPDATE TITLE & MIL/AERO STAMP.	11043	08/08/95	TL/



CONTROLLING DIMENSION IS INCH
VALUES IN [] ARE MILLIMETERS

NOTES: UNLESS OTHERWISE SPECIFIED

- LEAD FINISH TO BE ONE OF THE FOLLOWING:
 - 200 MICROINCHES/ 5.08 MICROMETERS MINIMUM SOLDER MEASURED AT THE CREST OF THE MAJOR FLATS.
 - 200 TO 800 MICROINCHES/ 5.08 TO 10.16 MICROMETERS TIN PLATE OVER 50 TO 300 MICROINCHES/ 1.27 TO 7.62 MICROMETERS NICKEL UNDERPLATE OR BASIS METAL.
 - 50 TO 100 MICROINCHES/ 1.27 TO 2.54 MICROMETERS GOLD OVER 50 TO 350 MICROINCHES/ 1.27 TO 8.89 MICROMETERS NICKEL UNDERPLATE.
- REFERENCE JEDEC REGISTRATION MO-058, VARIATION AA, DATED JULY 1989.

**MIL-PRF-38535
CONFIGURATION CONTROL**

APPROVALS	DATE	National Semiconductor		
DRAWN: T. LEQUANG	08/08/95	2900 Semiconductor dr., Santa Clara, CA 95052-8090		
DFTG. CHK.		CERDIP, 24 LEAD, .300 CENTERS		
ENGR. CHK.				
		SCALE: N/A	SIZE: C	REV: H
		DO NOT SCALE DRAWING	DRAWING NUMBER: MKT-J24F	SHEET 1 of 1